

Monday, September 12

12:00–13:00 (CET)	Welcome Desk & Fingerfood
13:00–13:30	Opening & Introduction Frank Brückner Fraunhofer IWS
13:30–13:55	Achievements and Challenges in Copper AM - an OEM's perspective Jens Karnapp EOS GmbH
13:55–14:20	Manufacturing and utilization of pure copper open porous structures <i>Robert Otto</i> <i>Siemens AG</i>
14:20–14:45	Copper applications in the accelerator industry Andris Ratkus Riga Technical University
14:45–15:20	Coffee Break
15:20–15:45	Cu and Cu-alloy manufacturing by Fused Filament Fabrication <i>Aljoscha Roch</i> <i>AM Extrusion GmbH</i>
15:45–16:10	Using a bi-modal particle size distribution for Binder Jetting of copper Moritz Greifzu Fraunhofer IWS
16:10–16:35	Topic: Binder Jetting, title tbd <i>Lorenzo Marchetti Digital Metal</i>
16:35–17:00	Wire electron beam additive manufacturing of copper Bernd Baufeld pro-beam GmbH & Co. KGaA
17:00–19:00	Time for hotel check-in
19.00-22.00	Social Event @ Fraunhofer Campus

Tuesday, September 13

08:30–09:00 (CET)	Welcome Desk
09:00–09:25	Algorithmic Programming – a novel approach for Additive Manufacturing Designs Josefine Lissner Hyperganic Group GmbH
09:25–09:50	Additive Manufacturing of Pure Copper with Green Laser Light <i>Michael Thielmann</i> <i>TRUMPF SE</i> + Co. KG
09:50–10:40	Lab Tour @ Fraunhofer IWS
10:40-11:00	Coffee Break
11:00–11:25	LPBF of pure copper and copper alloys using a green laser source Samira Gruber Fraunhofer IWS
11:25–11:50	Multi material processing for tooling applications Mirko Riede Fraunhofer IWS
11:50–12:15	Laser Direct Metal Deposition of Copper Based Materials Sandro Mehner Fraunhofer USA
12:15–12:30	Closing Remarks
12:30-13:30	Networking & Lunch